

ABSTRACT OF THE DISCLOSURE

A burn-in process for a semiconductor integrated circuit device includes a first process of positioning bump electrodes of the semiconductor integrated circuit device with respect to pads of a socket having detachment mechanisms, a second process of pressing the bump electrodes against the pads by weighting the semiconductor integrated circuit device, and a third process of detaching the bump electrodes from the pads by exerting force on the semiconductor integrated circuit device in a direction opposite to a weighting direction of the second process. Automatic insertion and detachment of a semiconductor integrated circuit chip in a burn-in test is facilitated by detaching the bump electrodes from the pads by pushing up the semiconductor integrated circuit device.